



CW12D1800 Data Sheet

Dual Channel 12-bit, 1.8 GSPS High Speed ADC

1. Overview

The CW12D1800 is a 12-bit high-speed ADC product with two built-in 12-Bits.

1.8 GSPS high-speed ADC, each channel ADC has independent DDR data clocks (DCLKI and DCLKQ). When both channel ADC are operating, DCLKI and DCLKQ are always in phase, so only one of them can be used to collect all data. If 1:2 Demux mode is selected, another set of 12-Bit LVDS buses are enabled so that the data rate of each set of LVDS changes to 1/2 of the Non-Demux mode to reduce the timing requirements for data capture.

The CW12D1800 supports AutoSync function and can be used for multi-chip cascade. The product package is plastic-sealed BGA292 package, with an operating temperature of $-55^{\circ}\text{C} \sim 105^{\circ}\text{C}$. The CW12D1800 achieves excellent dynamic performance with low power consumption below 2.4W.

The data output format of the CW12D1800 can be programmed to offset binary code and complement code, and output data using an LVDS interface that complies with international common standards. The output common mode can be adjusted at two voltages: 0.8V and 1.2V.

CW12D1800 and CW12D1600/ CW12D1000/CW10D1500/ CW10D1000 pin compatible.

2 Applications

- RF direct down-conversion
- High-speed data acquisition system
- Ultra-wideband satellite data reception
- Automatic test equipment
- High-speed test instrument
- Wideband radar
- Electronic countermeasures

3 Features

- Built-in dual-channel 1.8 GSPS ADC
- Low power consumption, no heat sink required
- Built-in terminal resistor (automatic calibration), buffer
- Provides test sequences for system debugging and batch testing
- 1:1 Non-Demux or 1:2 Demux LVDS data output
- Multi-chip automatic synchronization function
- Single power supply 1.9 V
- 292-BGA (27mm × 27mm × 1.7mm, 1.27mm ball spacing)
- Pin and CW12D1600/CW12D1000/CW10D1500/CW10D1000 compatible

4 Performance indicators

- Full power bandwidth: 3.0 GHz
- Data delay: 28 master clock cycles
- Static performance: DNL $-0.9/+1.5$ LSB, INL $-2.3/+2.8$ LSB
- Dynamic performance ($f_s = 1.8$ GSPS, input signal power -1 dBFS)
 - $f_{in}=248\text{MHz}$
ENOB = 8.7 Bit, SFDR = 64.7 dBFS, SNR = 54.1 dBFS
 - $f_{in}=498\text{MHz}$
ENOB = 8.5 Bit, SFDR = 64.8 dBFS, SNR = 52.8 dBFS
 - $f_{in} = 998 \text{ MHz}$
ENOB = 8.0 Bit, SFDR = 60.1 dBFS, SNR = 49.9 dBFS
 - $f_{in}=1147 \text{ MHz}$
ENOB = 7.9 Bit, SFDR = 60.1 dBFS, SNR = 49.4 dBFS
 - $f_{in}=1448 \text{ MHz}$
ENOB = 7.7 Bit, SFDR = 59.3 dBFS, SNR = 48.5 dBFS

5 Simplified block diagram

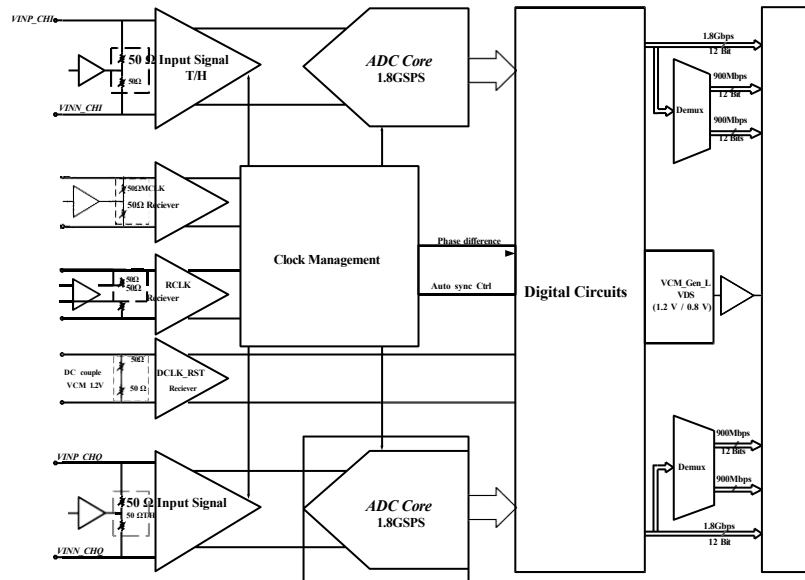


Figure 5.1 CW12D1800 system block diagram

6 Typical Performance

Table 6-1 Chip usage conditions

Parameter	Symbol	Comments	Value	Units
Power supply voltage	V_A	Analog circuit power supply	1.9	V
	V_{TC}	Sample hold and clock circuit power supply	1.9	V
	V_{DR}	Output driver circuit power supply	1.9	V
	V_E	Digital circuit power supply	1.9	V
Power-on sequence		No power-on sequence requirement		
Ground	GND	Analog circuit ground	0	V
	GND _{TC}	Sample hold and clock circuit ground	0	V
	GND _{DR}	Output driver circuit ground	0	V
	GND _E	Digital circuit ground	0	V
Differential input analog signal amplitude	$V_{inIp} - V_{inIn}$ $V_{inQp} - V_{inQn}$	Channel analog input signal differential amplitude	800	mVpp
Logic input high level	V_I		V_A	V
Logic input low level	V_{IL}		GND	
Clock differential input signal amplitude	$V_{CLKP} - V_{CLKN}$	Clock input signal differential amplitude	600	mVpp
Clock frequency	f_{CLK}		$0.5 \leq f_{CLK} \leq 1.8$	GHz
Operating temperature range	T_C		$-55 \leq T_C \leq 105$	°C

Table 6-2 Thermal resistance parameters

parameter	symbol	Typical values	unit
Thermal resistance between the junction and the environment	$R_{\theta JA}$	22.9	°C/W
Thermal resistance between the junction and the top of the package	$R_{\theta JC}$	7.7	°C/W
Thermal resistance between the junction and the circuit board	$R_{\theta JB}$	17.9	°C/W

Table 6-3 Electrical characteristics of power supply, input and output

The chip operates in Demux and Non-DES modes, and $V_A = V_{DR} = V_{TC} = V_E = +1.9V$, AC coupled signal input, unused channel termination is connected to "AC ground", AC coupled sine wave sampling clock, $f_{CLK} = 1.8\text{ GHz}$; $R_{ext} = R_{trim} = 3300\ \Omega \pm 0.1\%$; input source impedance $50\ \Omega$; $T_A = 25\ ^\circ\text{C}$.

parameter	symbol	Minimum value	Typical values	Maximum value	unit
Resolution			12		
Power supply voltage:					
Analog circuit power supply	V _A	1.8	1.9	2.0	V
Sampling and holding and clock circuit source	V _{TC}	1.8	1.9	2.0	V
Output drive circuit	V _{DR}	1.8	1.9	2.0	V
power supply					
Digital circuit power supply	V _E	1.8	1.9	2.0	V
Power supply current:					
Analog circuit power supply	I _A		19		mA
Sampling and holding and clock circuit source	I _{TC}		680		mA
Output drive circuit power supply	I _{DR}		370		mA
Digital circuit power supply	I _E		185		mA
Power consumption	P _D				
PDI = PDQ = GND			2.38		W
PDI = GND, PDQ = V _A			1.2		W
PDI = V _A , PDQ = GND			1.2		W
PDI = V _A , PDQ = V _A			1.9		mW
Data input					
Input differential analog signal amplitude	V _{inIp} – V _{inIn}		800		mV _{pp}
	V _{inQp} – V _{inQn}		800		mV _{pp}
Differential input resistance	R _{IN}	95	100	105	Ω

Table 6-4 Electrical characteristics of power supply, input and output (continued)

Parameter	Symbol	Minimum value	Typical value	Maximum value	Unit
Clock input					
Clock source type		Differential sine wave			
Clock input differential swing	$V_{CLKP} - V_{CLKN}$	400	600	1000	mVpp
Clock differential input resistance	R_{CLK}	95	100	105	Ω
External clock jitter requirement	Jitter			100	fs
Clock duty cycle requirement	Duty Cycle	40	50	60	%
Multi-chip DCLK_RST Sync signal					
Logic compatibility	LVDS				
Input voltage:					
Logic low	V_{IL_DRST}			1.1	V
Logic high	V_{IH_DRST}	1.3			V
Swing	V_{ID_DRST}		350		mV
Common-mode voltage	V_{CM_DRST}		1.20		V
Input resistance	R_{DRST}	95	100	105	Ω
Multi-chip RCLK synchronization signal					
Logic compatibility	LVDS				
Input voltage:					
Logic low	V_{IL_RCLK}			1.1	V
Logic high	V_{IH_RCLK}	1.3			V
Swing	V_{ID_RCLK}		350		mV
Common-mode voltage	V_{CM_RCLK}		1.20		V
Input resistance	R_{RCLK}	95	100	105	Ω
SPI					
Low-level input voltage	V_{IL_SPI}	0		$0.3 \times V_A$	V
High-level input voltage	V_{IH_SPI}	$0.7 \times V_A$		V_A	V
Low-level output voltage	V_{OL_SPI}			0.3	V
High-level output voltage	V_{OH_SPI}	1.6			V
Serial clock frequency	f_{SCLK}			10	MHz

Digital signal output (including data, clock and over-range indication; 50Ω transmission line, 100Ω differential termination)					
Logic compatibility	LVDS				
Swing (single-sided)	V _{OD}	300	350	400	mV _{pp}
Common-mode voltage	V _{CM_LVDS}		1.2/0.8		V
Output data delay	t _{LAT}		28		Sampling clock period
Data output rising edge (20 pF)	t _{LHT}		220		ps
Data output falling edge (20 pF)	t _{HLT}		220		ps
Clock data output deviation	t _{OSK}	180		350	ps
Clock data setup time (90°)	t _{SU}		350		ps
Clock data hold time (90°)	t _H		400		ps

Table 6-5 Static characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Differential nonlinearity	DNL	-0.84		1.16	LSB
Integral nonlinearity	INL	-2.54		2.85	LSB
Output offset error (offset error)	VOS		8		LSB
Full scale error (full scale error)	PFSE/NFSE		±15		mV

Table 6-6 Dynamic characteristics

Parameter		Symbol	Minimum	Typical	Maximum	Unit
Full power bandwidth:		FPBW		3.0		GHz
fs = 1.8 GSPS, Vin = -1 dBFS						
Effective number of bits	f _{in} = 248 MHz	ENOB		8.7		bit
	f _{in} = 498 MHz			8.4		bit
	f _{in} = 998 MHz			8.0		bit
	f _{in} = 1147 MHz			7.9		bit
	f _{in} = 1448 MHz			7.7		bit
Signal to Noise and Distortion Ratio	f _{in} = 248 MHz	SNDR		54.1		dBFS
	f _{in} = 498 MHz			52.6		dBFS
	f _{in} = 998 MHz			49.8		dBFS
	f _{in} = 1147 MHz			49.2		dBFS
	f _{in} = 1448 MHz			48.1		dBFS
Signal to Noise Ratio	f _{in} = 248 MHz	SNR		54.1		dBFS
	f _{in} = 498 MHz			52.8		dBFS
	f _{in} = 998 MHz			49.9		dBFS
	f _{in} = 1147 MHz			49.4		dBFS
	f _{in} = 1448 MHz			48.5		dBFS
Total Harmonic Distortion	f _{in} = 248 MHz	THD		70.8		dBFS
	f _{in} = 498 MHz			64.7		dBFS
	f _{in} = 998 MHz			65.8		dBFS
	f _{in} = 1147 MHz			63.8		dBFS
	f _{in} = 1448 MHz			59.1		dBFS
Spurious Free Dynamic Range	f _{in} = 248 MHz	SFDR		64.7		dBFS
	f _{in} = 498 MHz			64.8		dBFS
	f _{in} = 998 MHz			60.1		dBFS
	f _{in} = 1147 MHz			60.1		dBFS
	f _{in} = 1448 MHz			59.3		dBFS
Second Harm	f _{in} = 248 MHz	2nd Harm		79.3		dBFS
	f _{in} = 498 MHz			83.1		dBFS
	f _{in} = 998 MHz			82.7		dBFS
	f _{in} = 1147 MHz			82.8		dBFS
	f _{in} = 1448 MHz			76.7		dBFS
Third Harm	f _{in} = 248 MHz	3rd Harm		83.2		dBFS
	f _{in} = 498 MHz			74.5		dBFS
	f _{in} = 998 MHz			75.4		dBFS
	f _{in} = 1147 MHz			70.6		dBFS
	f _{in} = 1448 MHz			67.5		dBFS

Table 6-7 Calibration characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Calibration period	t_{CAL}		8×10^5		Sampling clock period
Calibration low time	t_{CAL_L}	1000 ⁽¹⁾			Sampling clock period
Calibration high time	t_{CAL_H}	1000 ⁽¹⁾			Sampling clock period
Calibration delay time	t_{CalDly}		1600		Sampling clock period

7 Pin configuration and function description

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	GND	V_A	SDD	TPM	NDM	V_A	GND	V_E	GND_E	Dk0p	V_DR	Dk3p	GND_DR	Dk6p	V_DR	Dk9p	GND_DR	Dk11p	Dk11n	GND_DR	A
B	VCM_LVDS	GND	ECGp	SDI	CalRun	V_A	GND	GND_E	V_E	Dk0n	Dk2p	Dk3n	Dk5p	Dk6n	Dk8p	Dk9n	Dk10p	Dk0p	Dk1p	Dk1n	B
C	Rtrimp	DC_AC	Rexp	SCSb	SCLK	V_A	NC	V_E	GND_E	Dk1p	Dk2n	Dk4p	Dk5n	Dk7p	Dk8n	Dk10n	Dk0n	V_DR	Dk2p	Dk2n	C
D	DNC	Rtrinn	Rexn	GND	GND	CAL	DNC	V_A	V_A	Dk1n	V_DR	Dk4n	GND_DR	Dk7n	V_DR	GND_DR	V_DR	Dk3p	Dk4p	Dk4n	D
E	V_A	Ts0adep	DNC	GND													GND_DR	Dk5n	Dk5p	Dk5n	E
F	V_A	GND_TC	Ts0aden	DNC													GND_DR	Dk6p	Dk6n	GND_DR	F
G	V_TC	GND_TC	V_TC	V_TC													Dk7p	Dk7n	Dk8p	Dk8n	G
H	Vinlp	V_TC	GND_TC	V_A													Dk8p	Dk8n	Dk10p	Dk10n	H
J	Vinn	GND_TC	V_TC	TE_VREFT													V_DR	Dk11p	Dk11n	V_DR	J
K	GND	TE_VREFT	V_TC	GND_TC													DRp	DRn	DCLK_lp	DCLK_In	K
L	GND	TE_VREFB	V_TC	GND_TC													DRp	DRn	DCLK_Qp	DCLK_Qn	L
M	VinQ1	GND_TC	V_TC	TE_VREFB													GND_DR	DQ11p	DQ11n	GND_DR	M
N	VinQ2	V_TC	GND_TC	V_A													DQ8p	DQ8n	DQ10p	DQ10n	N
P	V_TC	GND_TC	V_TC	V_TC													DQ7p	DQ7n	DQ8p	DQ8n	P
R	V_A	GND_TC	V_TC	V_TC													V_DR	DQ6p	DQ6n	V_DR	R
T	V_A	GND_TC	GND_TC	GND													V_DR	DQ3n	DQ5p	DQ5n	T
U	GND_TC	CLKp	PD1	GND	GND	RCOUT_1n	DNC	V_A	V_A	DQd1n	V_DR	DQd4n	GND_DR	DQd7n	V_DR	V_DR	GND_DR	DQ2p	DQ4p	DQ4n	U
V	CLKn	DCLK_RSTp	PDQ	CalDy	DES	RCOUT_2p	RCOUT_2n	V_E	GND_E	DQd1p	DQd2n	DQd4p	DQd5n	DQd7p	DQd8n	DQd10n	DQ0n	GND_DR	DQ2p	DQ2n	V
W	DCLK_RSTn	GND	DNC	DDRPh	RCLKn	V_A	GND	GND_E	V_E	DQd3n	DQd2p	DQd3n	DQd5p	DQd6n	DQd8p	DQd9n	DQd10p	DQ0p	DQ1p	DQ1n	W
Y	GND	V_A	FSR	RCLKp	RCOUT_1p	V_A	GND	V_E	GND_E	DQd3p	V_DR	DQd3p	GND_DR	DQd6p	V_DR	DQd9p	GND_DR	DQd11p	DQd11n	GND_DR	Y
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	

Figure 7.1 Pin Configuration of CW12D1800 (Top View)

Table 7-1 Pin function description

Pin number	Symbol	Function
H1, J1 N1, M1	VinIp, VinIn VinQp, VinQn	I/Q channel differential signal input
U2, V1	CLKp, CLKn	Differential sampling clock signal input
V2, W1	DCLK_RSTp, DCLK_RSTn	Differential clock reset. Positive pulse reset DCLKI and DCLKQ output
C2	DC_AC	AC Couple selection port, chip internal default pull-down
B1	VCM_LVDS	LVDS output VCM Select, the chip defaults to pull-up
E2, F3	Tdiodep, Tdiode n	Temperature sensor diode positive and negative ports
J4, K2	TE_VREFT	REFT channel test output
L2, M4	TE_VREFB	REFB channel test output
D1, D7, E3, F4, W3, U7	DNC	Floating pin, cannot be connected to any potential
C7	NC	Null pin
C3, D3	Rextp, Rextn	External 3.3kΩ precision resistor port 1
C1, D2	Rtrimp, Rtrimn	External 3.3kΩ precision resistor port 2
Y4, W5	RCLKp, RCLKn	Synchronous reference clock input
Y5, U6 V6, V7	RCOut1p, RCOut1n RCOut2p, RCOut2n	Reference clock output 1 and output 2
V5	DES	Double-edge sampling mode selection, when the input is set to logic high, DES (Double Edge Sample) operating mode is selected, which means sampling the I-channel and Q-channel inputs in a time interleaving manner. When this input is set to logic low, the chip is in Non-DES operating mode, i.e., the I channel and Q channel operate independently. In Extended Control Mode (ECM, Extended Control Mode), this input is ignored, and the DES mode selection is controlled by the DES bit (address: 0h, bit 7) through the control register; the default is Non-DES mode operation. Internal chip silent Recognize pull down.
V4	CalDly	Calibration delay selection, the internal chip is pulled down by default.

D6	CAL	<p>Calibration initialization. The user can have the chip perform self-calibration by keeping the input high at least tCAL_H after keeping the input low at least tCAL_L. If this input remains high on power-on, automatic power-on calibration will be disabled. This pin is valid in both ECM and Non-ECM. In ECM, this pin is logical or operational with the CAL bit (address: 0h, bit 15) in the control register. Therefore, both pins and bits must be set to low and then either one must be set to high to perform</p> <p>Command calibration. The chip internal drop-down is pulled down by default.</p>
B5	CalRun	<p>Calibration flag output, this output is logically high power when performing the calibration process. flat. Otherwise this output is logic low.</p>
U3 V3	PDI PDQ	<p>I/Q channel shutdown control. Setting any input to logic high will turn off Close the corresponding I or Q channel. Set either input to logic low Will cause the corresponding I or Q channels to enter the working state after a certain time delay state. This pin is valid in both ECM and Non- ECM. In ECM In this case, each pin performs logic or operation with its respective bits. Therefore, no Whether this pin or the PDI and PDQ bits in the control register are available Used to close I and Q channels respectively (address: 0h, bit 11 and bit 10). The chip internal drop-down is pulled down by default.</p>
A4	TPM	<p>Test mode selection, when the input is logic high, the chip continuously outputs a set of repeated fixed digital sequences. In ECM, this input is ignored, and the test mode can only control the register TPM bits (address: 0h, bit 12) control. The chip internal drop-down is pulled down by default.</p>

A5	NDM	Non-Demux mode selection, setting this input to logic high will set the digital output bus to 1:1 Non-Demuxed mode. Setting this input to logic low will set the digital output bus to 1:2 Demuxed mode. This function is only controlled by pins and in ECM and
		Stay active during Non-ECM. The chip internal drop-down is pulled down by default.
Y3	FSR	Full scale input range selection. In Non-ECM, this input must be set to logic high; the full-scale differential input range for the I and Q channel inputs is set by this pin. In ECM, this input is ignored, and the full scale range of I and Q channel inputs is set by Addr:3h and Addr:Bh, respectively. Set to determine independently. The chip is pulled up by default.
W4	DDRPh	DDR phase selection. This input selects the 0°Data- to-DCLK phase relationship when the logic is low. When logic is high, it selects the 90°Data-to- DCLK phase relationship, i.e. the DCLK conversion indicates the middle of the valid data output. This pin is only valid when the chip is in 1:2 Demux mode, i.e. the NDM pin is set to logic low. In ECM, this input is ignored and the DDR phase is passed by the DPS bit (address: 0h, bit 14) Control register selection; default is 0° mode. The chip internal drop-down is pulled down by default.
B3	ECEb	Extended control enable. When this signal is valid (logic low), the extended function control is performed through the SPI interface. In this case, most direct control pins do not work. When the signal is invalid (logic high), the SPI interface is disabled and all SPI registers are reset to their default values. All available settings are controlled via the control pin. The chip is pulled up by default.

C4	SCSb	SPI chip selection, the internal chip is pulled up by default.
C5	SCLK	SPI serial clock, the chip internal drive is pulled down by default.
B4	SDI	SPI serial data input, the chip internal drop-down is pulled down by default.
A3	SDO	SPI serial data output
A2, A6, B6, C6, D8, D9, E1, F1, H4, N4, R1, T1, U8, U9, W6, Y2, Y6	V_A	Analog circuit power supply
G1, G3, G4, H2 J3, K3, L3, M3 N2, P1, P3, P4 R3, R4	V_TC	Sampling and hold and clock circuit power supply
AT1, A15, C18 D11, D15, D17 J17, J20, R17 R20, T17, U11 U15, U16, Y11 Y15	V_DR	Output Driver power

Table 7-1 Pin Function Description (continued)

Terminal number	symbol	Function
A8, B9, C8, V8 W9, Y8	V_E	Digital encoding circuit power supply
A1, A7, B2, B7 D4, D5, E4, K1 L1, T4, U4, U5 W2, W7, Y1, Y7 H8:N13	GND	Analog circuit ground
F2, G2, H3, J2 K4, L4, M2, N3 P2, R2, T2, T3 U1	GND_TC	Sample and Hold and Clock Circuitry Ground
A13, A17, A20 D13, D16, E17 F17, F20, M17 M20, U13, U17 V18, Y13, Y17 Y20	GND_DR	Output Driver Ground
A9, B8, C9, V9 W8, Y9	GND_E	Digital encoding circuit ground
K19, K20 L19, L20	DCLKIp, DCLKIn DCLKQp, DCLKQn	I/Q channel data clock LVDS output
K17, K18 L17, L18	ORIp, ORIn ORQp, ORQn	I/Q channel overrange LVDS output
J18, J19 H19, H20 H17, H18 G19, G20 G17, G18 F18, F19 E19, E20 D19, D20 D18, E18 C19, C20 B19, B20 B18, C17	DQ11p, DQ11n DQ10p, DQ10n DQ9p, DQ9n DQ8p, DQ8n DQ7p, DQ7n DQ6p, DQ6n DQ5p, DQ5n DQ4p, DQ4n DQ3p, DQ3n DQ2p, DQ2n DQ1p, DQ1n DQ0p, DQ0n	I/Q channel data LVDS output

Table 7-1 Pin Function Description (Continued)

M18, M19 N19, N20 N17, N18 P19, P20 P17, P18 R18, R19 T19, T20 U19, U20 U18, T18 V19, V20 W19, W20 W18, V17	DQ11p, DQ11n DQ10p, DQ10n DQ9p, DQ9n DQ8p, DQ8n DQ7p, DQ7n DQ6p, DQ6n DQ5p, DQ5n DQ4p, DQ4n DQ3p, DQ3n DQ2p, DQ2n DQ1p, DQ1n DQ0p, DQ0n	I/Q channel data LVDS output
Pin Number	Symbol	Function
A18, A19 B17, C16 A16, B16 B15, C15 C14, D14 A14, B14 B13, C13 C12, D12 A12, B12 B11, C11 C10, D10 A10, B10	DId11p, DId11n DId10p, DId10n DId9p, DId9n DId8p, DId8n DId7p, DId7n DId6p, DId6n DId5p, DId5n DId4p, DId4n DId3p, DId3n DId2p, DId2n DId1p, DId1n DId0p, DId0n	I/Q Channel data delay LVDS output
Y18, Y19 W17, V16 Y16, W16 W15, V15 V14, U14 Y14, W14 W13, V13 V12, U12 Y12, W12 W11, V11 V10, U10 Y10, W10	DQd11p, DQd11n DQd10p, DQd10n DQd9p, DQd9n DQd8p, DQd8n DQd7p, DQd7n DQd6p, DQd6n DQd5p, DQd5n DQd4p, DQd4n DQd3p, DQd3n DQd2p, DQd2n DQd1p, DQd1n DQd0p, DQd0n	

8 Typical performance test curve

Chip works at Demux and Non-DES mode, and $V_A = V_{DR} = V_{TC} = V_E = +1.9V$, AC-coupled signal input, unused channels terminated to “AC ground”, AC-coupled sine wave sampling clock, $f_{CLK} = 1.8\text{ GHz}$; $R_{ext} = R_{trim} = 3300\ \Omega \pm 0.1\%$; input signal source impedance $50\ \Omega$; $T_A = 25^\circ\text{C}$.

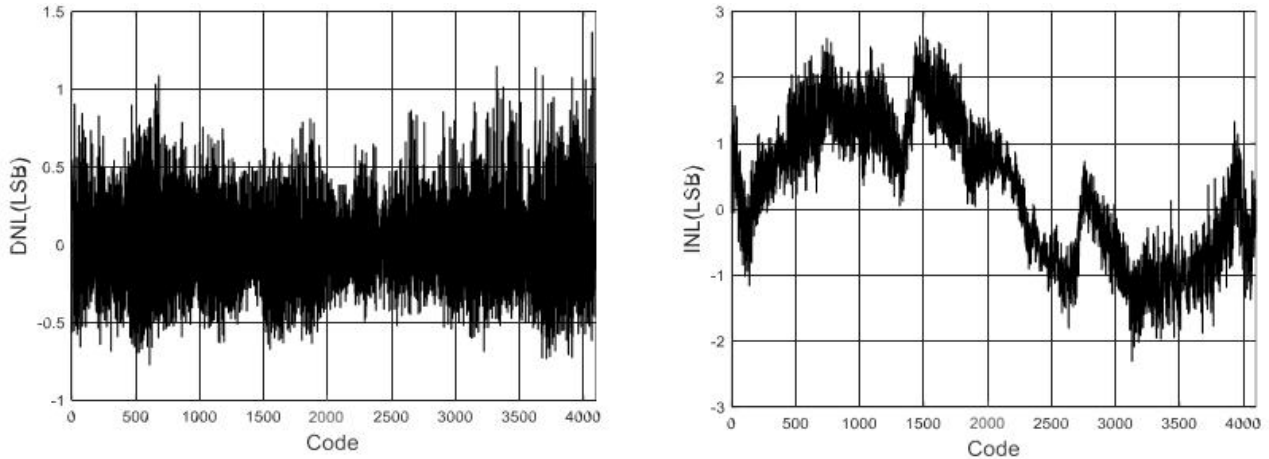


Figure 8.1 CW12D1800 Linear Error

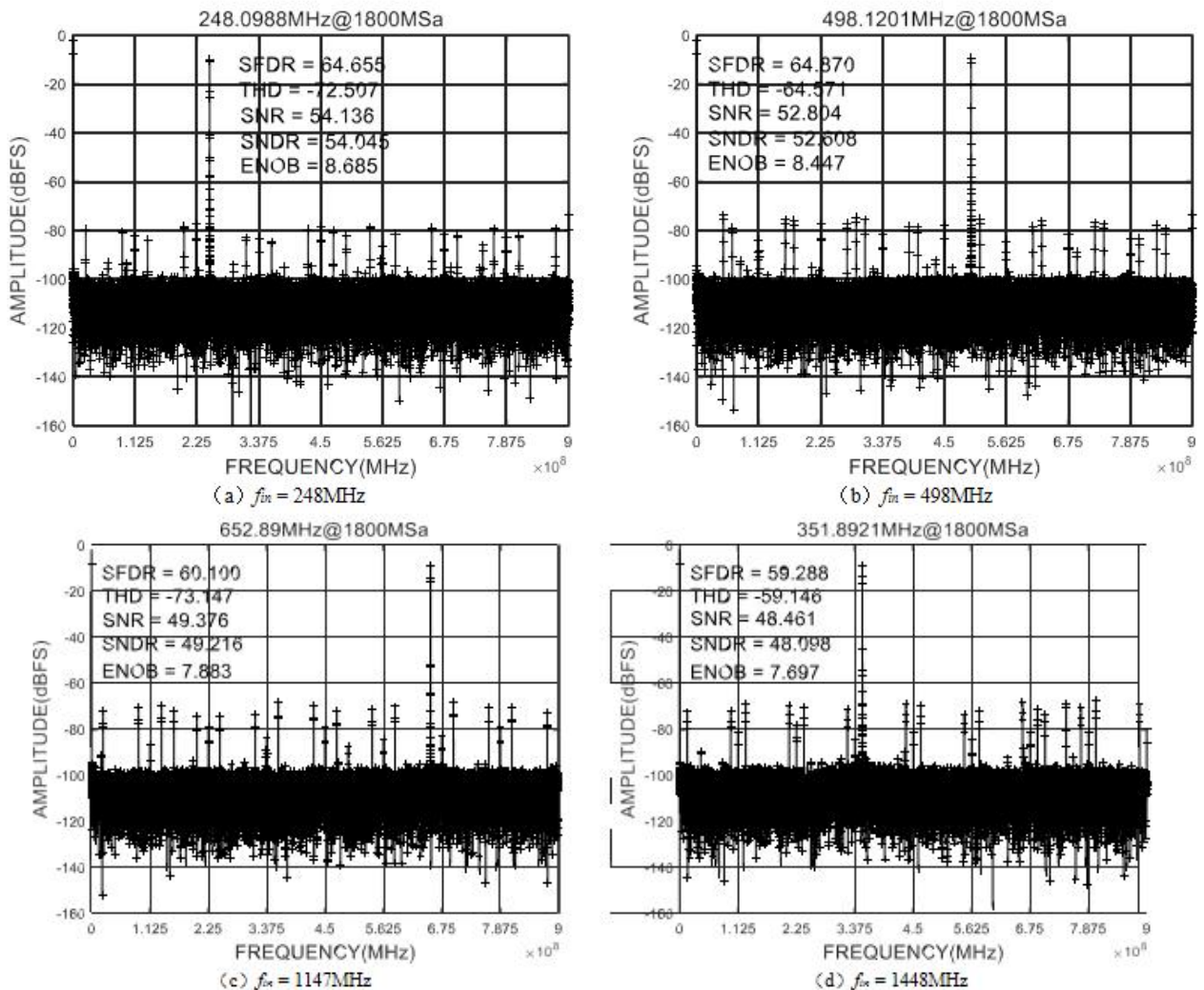


Figure 8.2 Dynamic Characteristics of CW12D1800D (FS=1.8GHz)

9 Timing diagram

1. Data timing

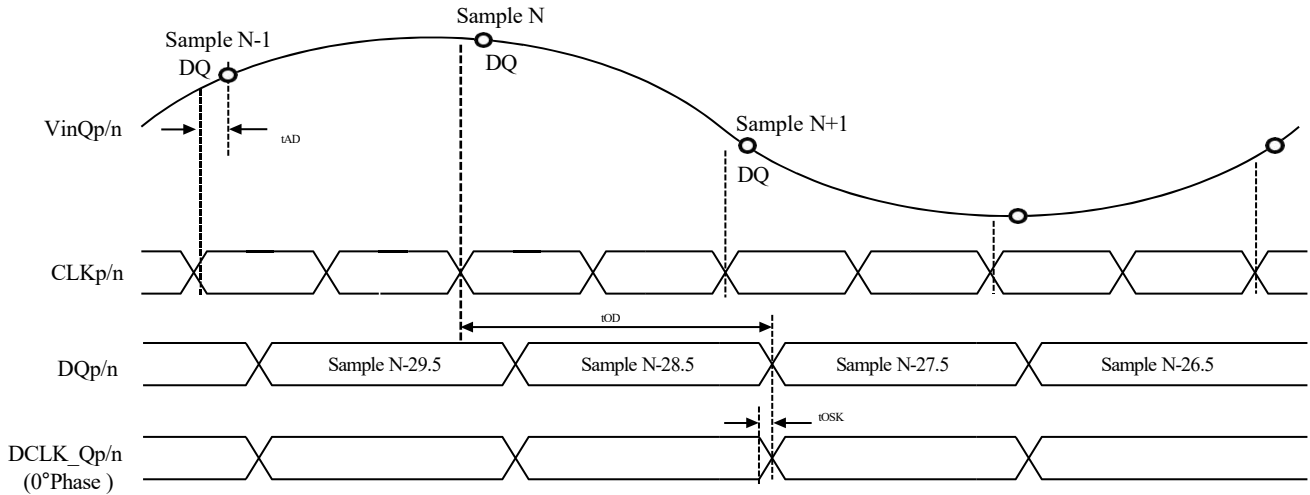


Figure 9.1 CW12D1800 data timing in Non-Demux Non-DES mode

Description:

The I channel data timing is exactly the same as the Q channel.

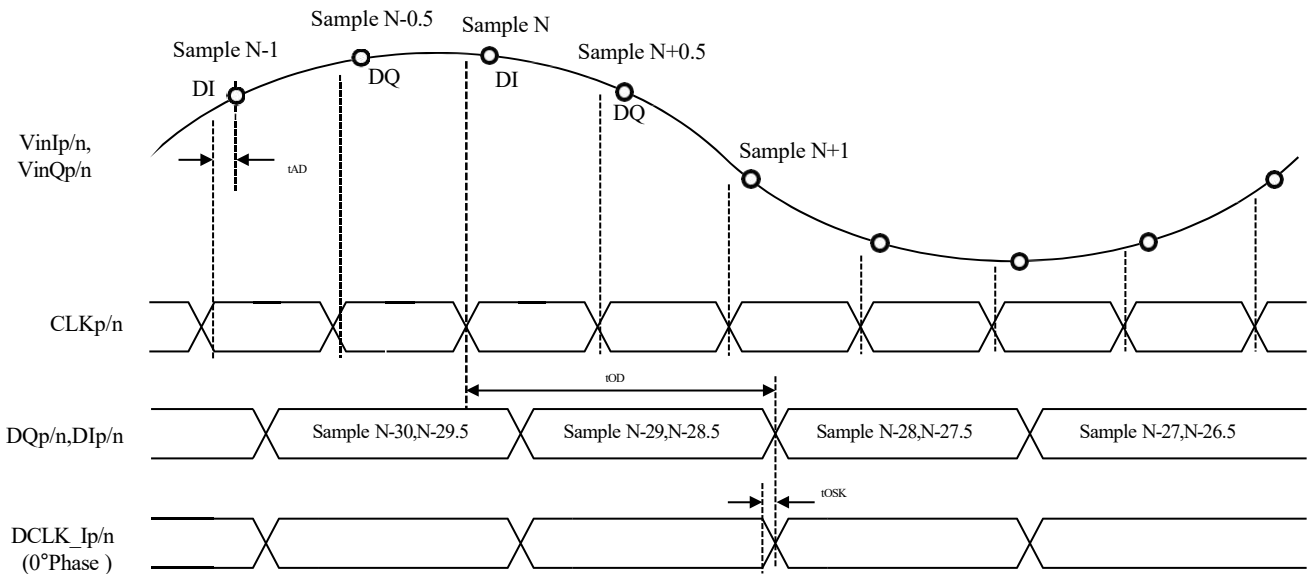


Figure 9.2 CW12D1800 data timing in Non-Demux DES mode

Description:

In this mode, VinIp/n and VinQp/n must be "short-circuited" at the ADC input; I channel input is sampled at the rising edge of CLK, and Q channel input is sampled at the falling edge of CLK; I Channel output delay 27.5 Cycles, Q channel output delay 28 Cycles;

Data is output on both edges of DCLK, the time sequence is DQ, DI (FDCLK = 1/2 FS)

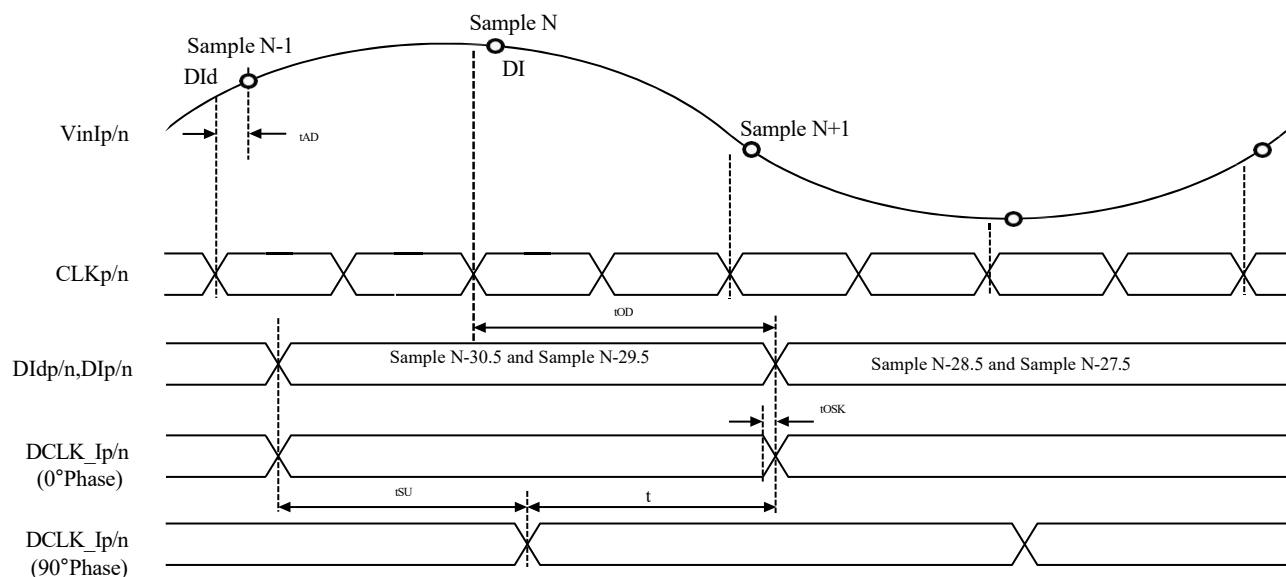


Figure 9.3 CW12D1800 data timing in 1:2 Demux Non-DES mode

Description:

I channel input is sampled on the rising edge of

CLK; I channel output is delayed by 27.5 cycles;

Data is output on both edges of DCLK, the time sequence is DId, DI (FDCLK = 1/4 FS)

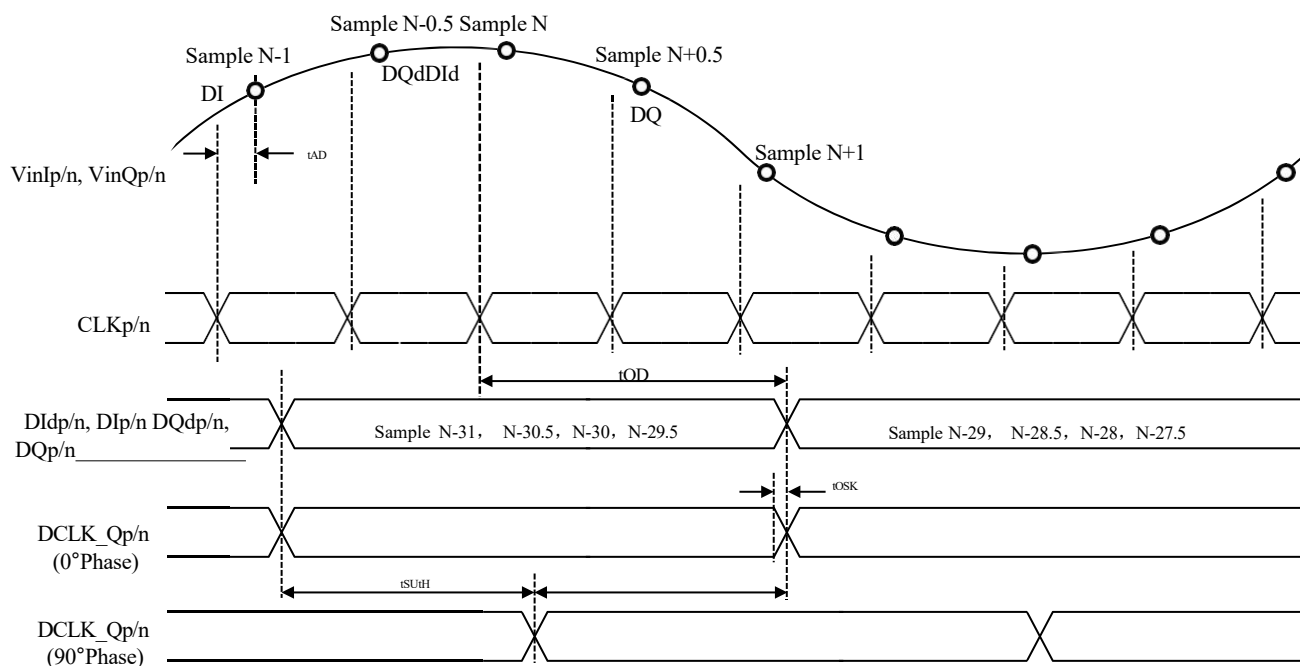


Figure 9.4 CW12D1800 Data Timing in 1:4 Demux DES Mode

Description:

In this mode, VinIp/n and VinQp/n must be "shorted" at the ADC input; I channel input is sampled at the rising edge of CLK, and Q channel input is sampled at the falling edge of CLK; I channel output delay is 27.5 cycles, Q channel output delay is 28 cycles;

Data is output at both edges of DCLK, the time sequence is DQ, DI (FDCLK = 1/4 FS)

9.2 Calibration Timing

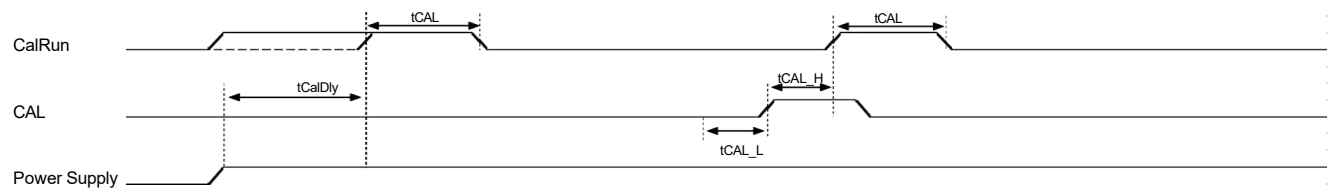


Figure 9.5 Power-on Calibration and On-Command Calibration Timing

9.3 SPI Interface Timing

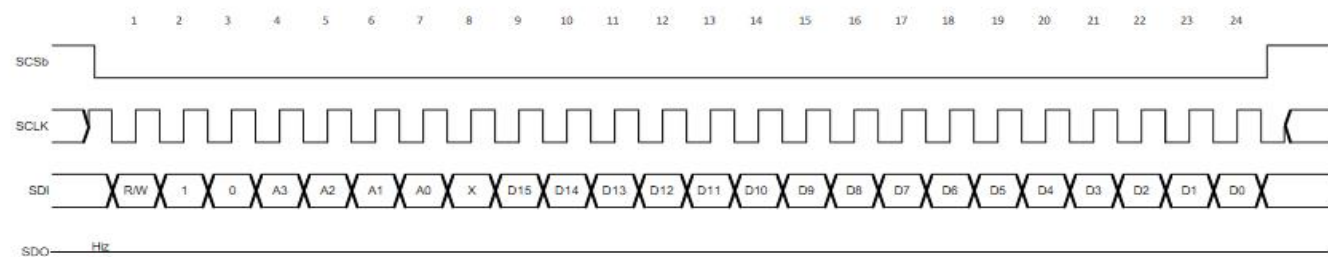


Figure 9.6 SPI write timing

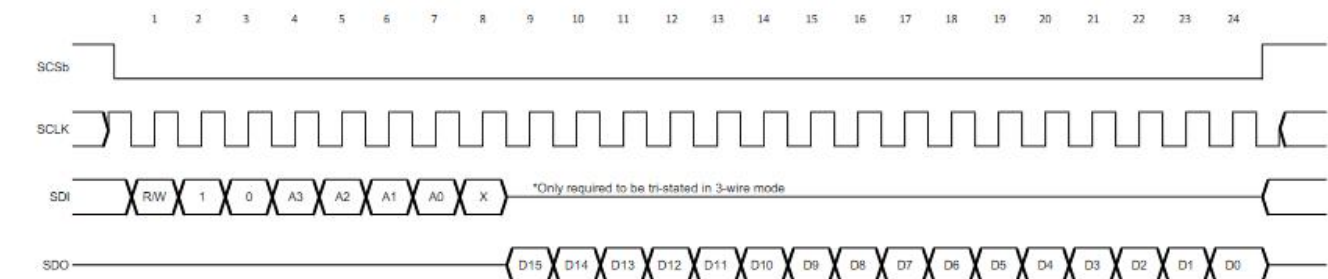
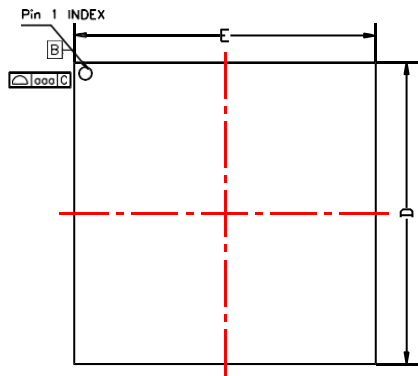


Figure 9.7 SPI read timing

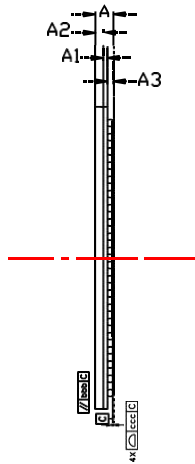
Table 9.1 SPI interface command and data field definition

Bit	Definition	Description
1	Read/write control bit	1b: read operation 0b: write operation
2~3	Reserved	Default setting is 10b
4~7	Address bit A[3:0]	Register address, address order is MSB first
8	X	Reserved
9~24	Data bit D[15:0]	Data is written to or read from the register

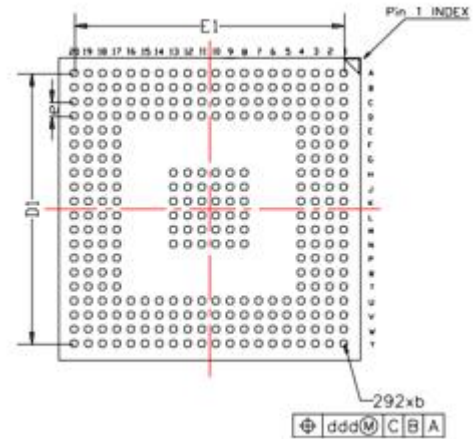
10 Package information



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Figure 10.1 CW12D1800 package outline

Table 10.1 CW12D1800 package outline dimensions

Dimension symbol	Unit: mm		
	Minimum	Typical	Maximum
A	1.56	1.66	1.76
A1	0.32	0.36	0.40
A2	-	0.7	-
A3	0.55	0.6	0.65
D	-	27.0	-
E	-	27.0	-
D1	-	24.13	-
E1	-	24.13	-
e	-	1.27	-
b	0.71	0.76	0.81

port	Connection suggestions
RCLKp/RCLKn	Floating
RCOUT1p/RCOUT1n	Floating
RCOUT2p/RCOUT2n	Floating
DCLK_RST+	Connect to GND via a 1kΩ resistor
DCLK_RST-	Connect to VA via 1kΩ resistor

12 Register list

Configuration Register 1

Addr: 0h (0000b)									POR state: 2000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	CAL	DPS	OVS	TPM	PDI	PDQ	Res	Res	DES	Res	Res	SC	Res			
POR	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15	CAL, calibration enable bit Setting CAL=1 will trigger a correction process. Since this control bit will not be automatically cleared, when the user triggers correction, CAL=0 must be set in advance Both this control bit and the CAL pin can trigger the correction process, which is functionally a "or" relationship, and has no polarity requirement between each other.															
Bit 14	DPS, DDR phase difference selection bit When DPS=0, the DDR Data-to-DCLK phase relationship is 0° When DPS=1, the DDR Data-to-DCLK phase relationship is 90° In Non-Demux mode, this bit setting is invalid and is always in DDR 0° mode.															
Bit 13	OVS, output voltage selection bit When OVS=0, the output voltage is 0.8V. When OVS=1, the output voltage is 1.2V. This control bit is the LVDS output pin (DATA, OR and DCLK), and different voltages are selected															
Bit 12	TPM, test mode enable bit When TPM=0, normal working mode When TPM=1, the device's LVDS output pin (Digital DATA, OR) will continuously output a fixed digital pattern															
Bit 11	PDI, I channel power-off enable bit When PDI=0, the I channel is in normal working mode When PDI=1, the I channel is in shutdown working mode This control bit and the PDI pin are functionally "OR" related. As long as any signal is valid (high level), the I channel will be in power-off mode															
Bit 10	PDQ, Q channel power-off enable bit When PDQ=0, the Q channel is in normal working mode When PDQ=1, the Q channel is in shutdown working mode This control bit and the PDQ pin are functionally "OR" related. As long as any signal is valid (high level), the Q channel will be in power-off mode															

Addr: 0h (0000b)									POR state: 2000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	CAL	DPS	OVS	TPM	PDI	PDQ	Res	Res	DES	Res	Res	SC	Res			
POR	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 9	Reserved															
Bit 8	Reserved															
Bit 7	DES, dual-edge sampling enable bit When DES=0, the device works in single-edge sampling mode (Non-DES Mode) When DES=1, the device works in dual-edge sampling mode (DESIQ Mode), and the I/Q channels need to be shorted															
Bit 6	DEQ, reserved word, Reserved															
Bit 5	DIQ, reserved word, Reserved															
Bit 4	SC, binary complement enable bit When SC=0, the LVDS data output format is offset binary format (Offset Binary format) When SC=1, the LVDS data output format is binary complement format (Two's Complement format)															
Bit 3:0	Reserved															

Reserved word

Addr: 1h (0001b)									POR state: 7335h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res															
POR	0	1	1	1	0	0	1	1	0	0	1	1	0	1	0	1
Bit 15:0	Reserved															

I channel offset configuration word

Addr: 2h (0010b)									POR state: 0000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res				OS		OM<11:0>									
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15:13	Reserved															
Bit 12	OS, offset direction When OS=0, Bits 11:0 represent the ADC output positive offset When OS=1, Bits 11:0 represent the negative offset of ADC output															
Bit 11:0	OM, offset size 1/4 LSB															

I channel full amplitude calibration configuration word

Addr: 3h (0011b)									POR state: 0280h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res						FM<9:0>									
POR	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0
Bit 15:10	Reserved															
Bit 9:0	FM, full scale amplitude setting, positive and negative adjustable 16mV, step length is about 63uV 0180 600mV 0280 800mV 0380 1000mV															



Calibration Configuration Word

Addr: 4h (0100b)									POR state: 0000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res								SSC	Res						
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15:8	Reserved															
Bit 7	SSC, SPI write enable bit When SSC=0, the user is prohibited from changing the calibration value (stored in 05h and 06h) When SSC=1, the user is allowed to change the calibration value (stored in 05h and 06h)															
Bit 6:0	Reserved															

I channel calibration value

Addr: 5h (0101b)									POR state: 0000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res															
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15:0	Reserved															

Q channel calibration value

Addr: 6h (0110b)									POR state: 0000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res															
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 3:0	Reserved															

DES timing adjustment word

Addr: 7h (0111b)									POR state: 8000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	DES1<9:0>								Res							DSL
POR	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15:6	DES phase setting, range 25ps, step length ~25fs															
Bit 5:1	Reserved															
Bit 0	DSL, Q channel DES phase selection 0: Select the value written to DES1 (default I/Q channel writes the value of DES1) 1: Select the value written to DES2															

Reserved word

Addr: 8h (1000b)									POR state: 7335h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res															
POR	0	1	1	1	0	0	1	1	0	0	1	1	0	1	0	1
Bit 15:0	Reserved															

Addr: 9h (1001b)									POR state: 7335h								
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	Res																
POR	0	1	1	1	0	0	1	1	0	0	1	1	0	1	0	1	
Bit 15:0	Reserved																

Q channel offset configuration word

Addr: Ah (1010b)									POR state: 0000h								
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	Res				OS	OM<11:0>											
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
Bit 15:13	Reserved																
Bit 12	OS, offset direction When OS=0, Bits 11:0 represent the ADC output positive offset. When OS=1, Bits 11:0 represent the ADC output negative offset.																
Bit 11:0	OM, offset size 1/4 LSB																

Q channel full amplitude calibration configuration word

Addr: Bh (1011b)									POR state: 0280h								
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	Res								FM<9:0>								
POR	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	
Bit 15:10	Reserved																
Bit 9:0	FM, full scale amplitude setting, positive and negative adjustable 16mV, step length is about 63uV 0180 600mV 0280 800mV 0380 1000mV																

Aperture delay coarse adjustment control word (reserved word)

Addr: Ch (1100b)									POR state: 0400h								
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Name	CAS1<5:0>						Res									CTS	
POR	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	
Bit 15:10	tAD coarse adjustment configuration, range 115ps, step length 23ps																
Bit 9:1	Reserved																
Bit 0	CTS, Q channel tAD coarse adjustment configuration selection 0: Select the configuration written to CAS1 (I channel always uses CAS1) 1: Select the configuration written to CAS2																

Aperture delay fine adjustment control word

Addr: Dh (1101b)									POR state: 8000h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	FAS1<9:0>									Res						FTS
POR	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Bit 15:6	tAD fine adjustment configuration, range 25ps, step length is about 25fs															
Bit 5:1	Reserved															
Bit 0	FTS, Q channel tAD fine adjustment configuration selection 0: Select the configuration written to FAS1 (I channel always uses FAS1) 1: Select the configuration written to FAS2															

AutoSync control word

Addr: Eh (1110b)									POR state: 0003h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res		DRC<5:0>						Res	SP<3:0>				ES	DOC	DR
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1
Bit 15:14	Reserved															
Bit 13:8	DRC<5:0>, reference clock RCLK internal delay control word, 64 configurations in total, 20ps as a step															
Bit 7	Reserved															
Bit 6:3	SP<3:0>, phase selection Used to select the phase difference of the reference clock RCLK, step size 22.5°															
Bit 2	ES, slave enable bit When ES=0, the device works in the host mode When ES=1, the device works in the slave mode															
Bit 1	DOC, disable the output of reference clock RCLK When DOC=0, enable the output of reference clock RCLK of RCOut1/2 ports. When DOC=1, disable the output of reference clock RCLK of RCOut1/2 ports.															
Bit 0	DR, disable DCLK_RST function When DR=0, enable DCLK_RST function. When DR=1, disable DCLK_RST function.															

Reserved word

Addr: Fh (1111b)									POR state: 7335h							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Res															
POR	0	1	1	1	0	0	1	1	0	0	1	1	0	1	0	1
Bit 15:0	Reserved															